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Approved Specification

Rev:A0

MODEL NO. : ET064AM03-WT

ISSUED DATE: _____

Proposed by			Customer's Approval
Designed	Checked	Approved	

This technical specification is subjected to change without notice.



Table of Contents	2
Record of Revision	3
1 General Specifications	4
2 Input/output Terminals	5
2.1 Main TP-FPC Pin Assignment	5
2.2 MCU and Display Module Interface Conflagration	6
3 Absolute Maximum Ratings	7
3.1 Driving AMOLED Panel	7
4 Electrical Characteristics	7
4.1 Driving AMOLED Panel	7
5 AC Characteristics	8
5.1 MIPI Interface Characteristics	8
5.2 Display RESET Timing Characteristics	10
6 Recommended Operating Sequence	11
6.1 Display Power on / off Sequence	11
7 Touch Specification	13
7.1 General Specifications	13
7.2 Electrical Characteristics	13
7.2.1 Maximum Ratings	
7.2.2 Power supply DC characteristics	
7.3 TP FPC Pin Assignment	13
7.4 Touch Design	14
7.5 TSP FPC Electronic Part List	14
8 Optical Characteristics Optical Specification	15
9 Environmental / Reliability Test	16
10 Quality Level	17
10.1 AMOLED Module of Characteristic Inspection	17
10.2 Sampling Procedures for Each Item Acceptance Table	23
10.3 Telecommunications Inspection Item	23
10.4 Appearance Inspection Item	25
10.5 Inspection picture library	31
11 Mechanical Drawing	33
12 Precautions for Use of AMOLED Modules	34
12.1 Handling Precautions:	34
12.2 Storage Precautions:	34
12.3 Transportation Precautions:	34



Rev	Issue Date	Description	Editor
A0	2024-06-21	Draft	Wang Chun



1 General Specifications

Feature		Spec	Remark
Display Spec	Screen Size (inch)	6.39	
	Display Mode	AMOLED	
	Display method	Active Matrix TFT	
	Resolution(dot)	1080(W)x2340(H)	
	Active Area(mm)	68.04(W)x147.42(H)	
	Pixel Pitch (um)	63 (W)×63(H)	
	Pixel Configuration	V-Style4	
	Technology Type	LTPS	
	Color Depth	16.7M	
	Interface	MIPI 4 LANE	
Mechanical Characteristics	Polarizer Surface Treatment	HC	2H
	With TP/Without TP	With TP	
	Module Outline Dimension(W x H x D) (mm)	69.84*150.42*0.798	Excluding Cover lens
Electronic	Driver IC(Type)	SD5207	
	Touch IC(Type)	FT3519	
	Frame Rate	60HZ	

Note 1: Requirements on Environmental Protection: RoHS2.0.



2 Input/output Terminals

2.1 Main TP-FPC Pin Assignment

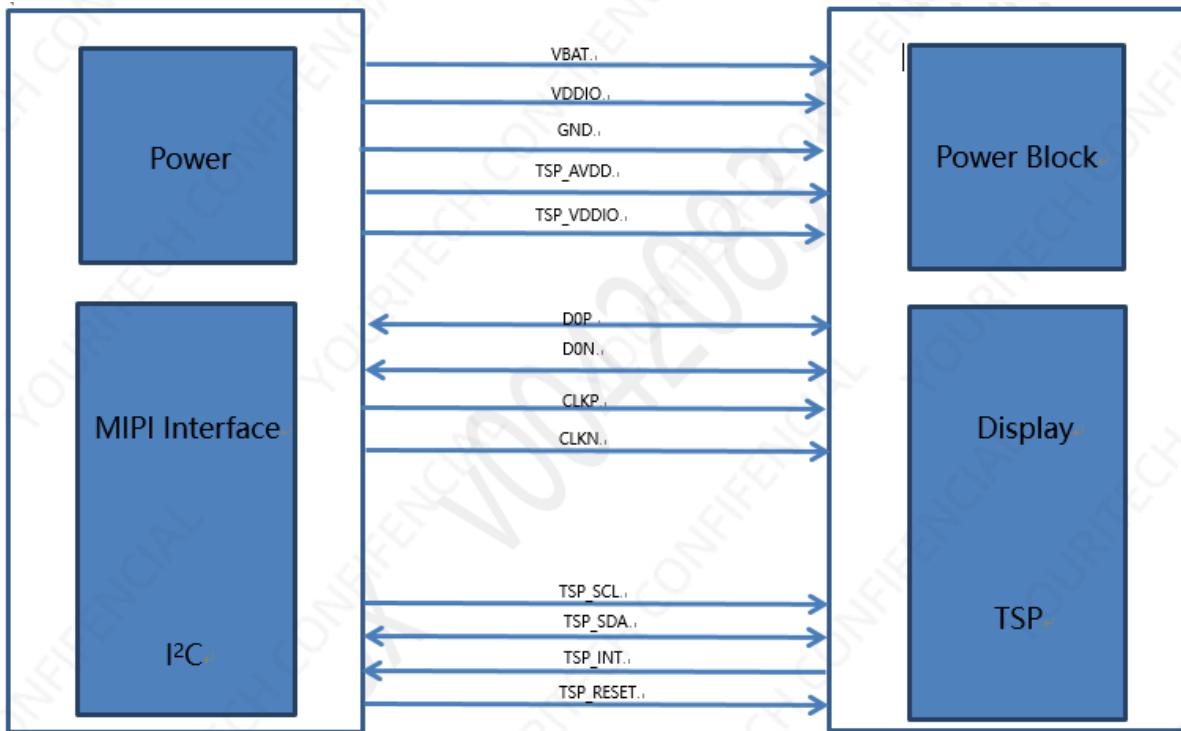
1	GND	Ground
2	D0P	MIPI Data Line
3	D0N	MIPI Data Line
4	GND	Ground
5	D1P	MIPI Data Line
6	D1N	MIPI Data Line
7	GND	Ground
8	CLKP	MIPI CLK Line
9	CLKN	MIPI CLK Line
10	GND	Ground
11	D2P	MIPI Data Line
12	D2N	MIPI Data Line
13	GND	Ground
14	D3P	MIPI Data Line
15	D3N	MIPI Data Line
16	GND	Ground
17	TSP_INT	Interrupt Signal for Touch Panel
18	TSP_RESET	Reset Pin for Touch Panel
19	TSP_SCL	Serial Clock Signal for Touch Panel I2C I/F
20	TSP_SDA	Serial Data Signal for Touch Panel I2C I/F
21	TSP_AVDD	Analog Power for Touch Panel
22	TSP_VDDIO	Digital Power for Touch Panel
23	AVDD	AMOLED charge pumping power for DDIC
24	AVDD_EN	AVDD enable
25	SWIRE	Control the PMIC
26	TE	Tear Effect
27	REST	Drive IC reset
28	VDDIO	AMOLED logic power for DDIC
29	GND	Ground (or NA)
30	ELVSS	AMOLED EL Negative power



31	ELVSS	
32	ELVSS	
33	GND	Ground (or NA)
34	ELVDD	AMOLED EL Positive power
35	ELVDD	
36	ELVDD	
37	MTP_PWR	Power supply for MTP Programming or Erase
38	VCI	AMOLED logic power for DDIC
39	DVDD	AMOLED logic power for DDIC

Note: I=Input; O=Output; P=Power; I/O=Input / Output

2.2 MCU and Display Module Interface Conflagration



3 Absolute Maximum Ratings

3.1 Driving AMOLED Panel

Maximum Ratings (Voltage Referenced to VSS) VSS=0V, Ta=25°C

Item	Symbol	MIN	MAX	Unit
Analog Power supply	VCI	-0.3	+5.5	V
Logic Power supply	VDDIO	-0.3	+5.5	V
Analog Power supply	AVDD	-0.3	8.8	V
Positive power for OLED	ELVDD	+4.0	+5.0	V
Negative power for OLED	ELVSS	-1.0	-5.0	V

Note: Functional operation should satisfy the limits in the Electrical Characteristics tables or Pin Description section. If the module exceeds the absolute maximum ratings, permanent damage may occur. Besides, if the module is operated with the absolute maximum ratings for a long time, the reliability may also drop.

4 Electrical Characteristics

4.1 Driving AMOLED Panel

Ta=25°C

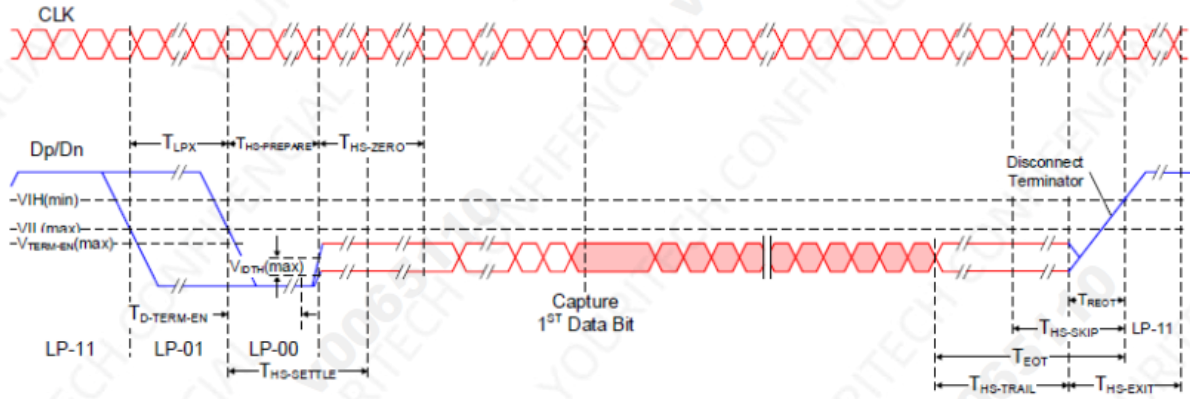
Item		Symbol	MIN	TYP	MAX	Unit
Logic Power supply		VDDIO	1.65	1.80	1.98	V
Analog Power supply		VCI	2.5	3.0	3.60	V
Analog Power supply		AVDD	4.5	7	8	V
Default Positive Output Voltage		ELVDD	4.55	4.60	4.65	V
Positive Output voltage total variation			-0.80	-	+0.80	%
Default Negative Output voltage		ELVSS	-1.00	-3.00	-4.00	V
Negative output voltage total variation			-1.00	-	+1.00	%
Input Signal Voltage	High Level	VIH	0.70*VDDIO	-	VDDIO	V
	Low Level	VIL	0.00	-	0.70*VDDIO	V
Output Signal Voltage	High Level	VOH	0.80*VDDIO	-	VDDIO	V
	Low Level	VOL	0.00	-	0.20*VDDIO	V

Note: The current and power consumption were tested under White pattern, 25°C

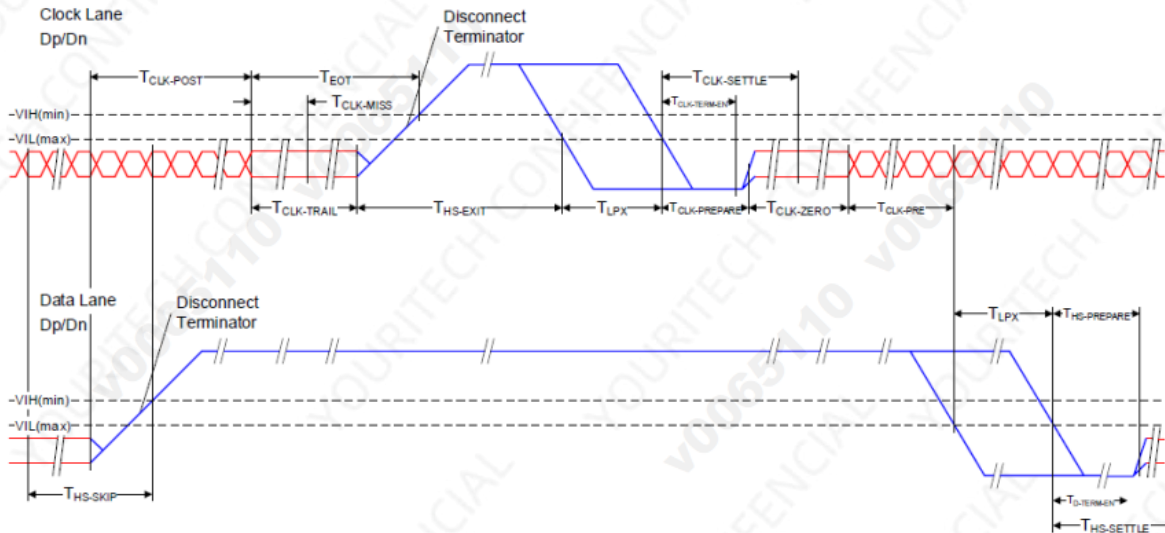


5 AC Characteristics

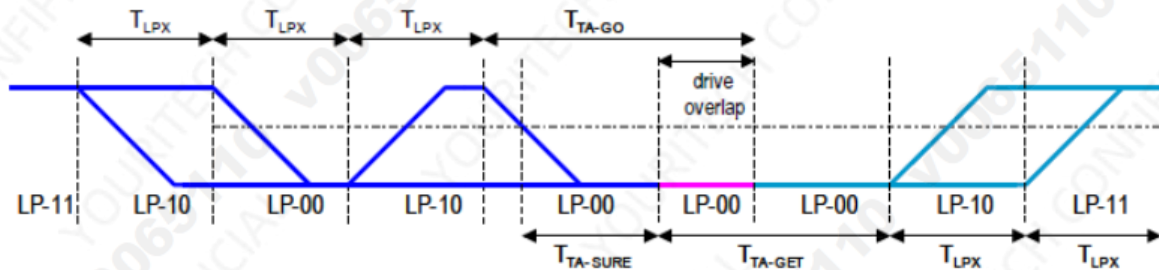
5.1 MIPI Interface Characteristics HS Data Transmission Burst



HS clock transmission



Turnaround Procedure



Timing Parameter:

Parameter	Description	Min	Typ	Max	Unit	Notes
T _{CLK-MISS}	Timeout for receiver to detect absence of Clock transitions and disable the Clock Lane HS-RX.			60	ns	1, 6
T _{CLK-POST}	Time that the transmitter continues to send HS clock after the last associated Data Lane has transitioned to LP Mode. Interval is defined as the period from the end of T _{HS-TRAIL} to the beginning of T _{CLK-TRAIL} .	60 ns + 52*UI			ns	5
T _{CLK-PRE}	Time that the HS clock shall be driven by the transmitter prior to any associated Data Lane beginning the transition from LP to HS mode.	8			UI	5
T _{CLK-PREPARE}	Time that the transmitter drives the Clock Lane LP-00 Line state immediately before the HS-0 Line state starting the HS transmission.	38		95	ns	5
T _{CLK-SETTLE}	Time interval during which the HS receiver should ignore any Clock Lane HS transitions, starting from the beginning of T _{CLK-PREPARE} .	95		300	ns	6, 7
T _{CLK-TERM-EN}	Time for the Clock Lane receiver to enable the HS line termination, starting from the time point when Dn crosses V _{ILMAX} .	Time for Dn to reach V _{TERM-EN}		38	ns	6
T _{CLK-TRAIL}	Time that the transmitter drives the HS-0 state after the last payload clock bit of a HS transmission burst.	60			ns	5
T _{CLK-PREPARE} + T _{CLK-ZERO}	T _{CLK-PREPARE} + time that the transmitter drives the HS-0 state prior to starting the Clock.	300			ns	5
T _{D-TERM-EN}	Time for the Data Lane receiver to enable the HS line termination, starting from the time point when Dn crosses V _{ILMAX} .	Time for Dn to reach V _{TERM-EN}		35 ns + 4*UI		6
T _{EOT}	Transmitted time interval from the start of T _{HS-TRAIL} or T _{CLK-TRAIL} to the start of the LP-11 state following a HS burst.			105 ns + n*12*UI		3, 5
T _{HS-EXIT}	Time that the transmitter drives LP-11 following a HS burst.	100			ns	5

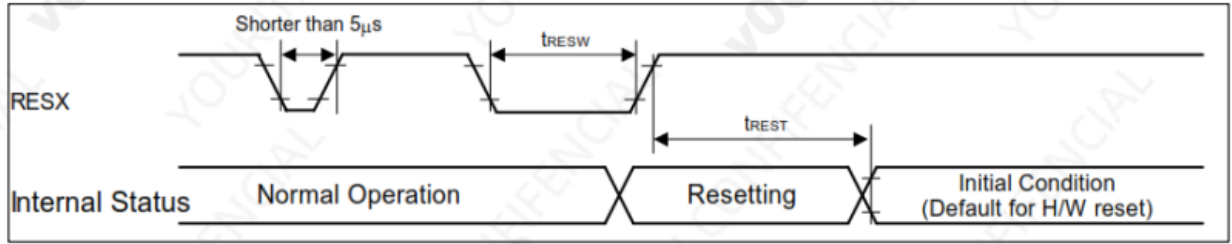
Parameter	Description	Min	Typ	Max	Unit	Notes
T _{HS-PREPARE}	Time that the transmitter drives the Data Lane LP-00 Line state immediately before the HS-0 Line state starting the HS transmission	40 ns + 4*UI		85 ns + 6*UI	ns	5
T _{HS-PREPARE} + T _{HS-ZERO}	T _{HS-PREPARE} + time that the transmitter drives the HS-0 state prior to transmitting the Sync sequence.	145 ns + 10*UI			ns	5
T _{HS-SETTLE}	Time interval during which the HS receiver shall ignore any Data Lane HS transitions, starting from the beginning of T _{HS-PREPARE} . The HS receiver shall ignore any Data Lane transitions before the minimum value, and the HS receiver shall respond to any Data Lane transitions after the maximum value.	85 ns + 6*UI		145 ns + 10*UI	ns	6
T _{HS-SKIP}	Time interval during which the HS-RX should ignore any transitions on the Data Lane, following a HS burst. The end point of the interval is defined as the beginning of the LP-11 state following the HS burst.	40		55 ns + 4*UI	ns	6
T _{HS-TRAIL}	Time that the transmitter drives the flipped differential state after last payload data bit of a HS transmission burst	max(n*8*UI, 60 ns + n*4*UI)			ns	2, 3, 5
T _{INIT}	See Section 6.11.	100			μs	5
T _{LPX}	Transmitted length of any Low-Power state period	50			ns	4, 5
Ratio T _{LPX}	Ratio of T _{LPX(MASTER)} /T _{LPX(SLAVE)} between Master and Slave side	2/3		3/2		
T _{TA-GET}	Time that the new transmitter drives the Bridge state (LP-00) after accepting control during a Link Turnaround.	5*T _{LPX}			ns	5
T _{TA-GO}	Time that the transmitter drives the Bridge state (LP-00) before releasing control during a Link Turnaround.	4*T _{LPX}			ns	5
T _{TA-SURE}	Time that the new transmitter waits after the LP-10 state before transmitting the Bridge state (LP-00) during a Link Turnaround.	T _{LPX}		2*T _{LPX}	ns	5
T _{WAKEUP}	Time that a transmitter drives a Mark-1 state prior to a Stop state in order to initiate an exit from ULPS.	1			ms	5

Note 1: VDDIO/VDDAM/VDDR =1.65~3.6V, VCI=2.5 to 3.6V, VSSIO=DVSS=VSSA=VSSAM=VSSR =VSSB=0V, Ta=-30 to +85 °C.



5.2 Display RESET Timing Characteristics

Reset input timing:



Symbol	Parameter	Related Pins	Min.	Typ.	Max.	Note	Unit
tRESW	*1) Reset low pulse width	RESX	10	-	-	-	us
tREST	*2) Reset complete time				5	When reset applied during sleep in mode	ms
					120	When reset applied during Sleep out mode	ms

Note 5: It is necessary to wait 5msec after releasing RSTB before sending commands. Also Sleep Out command cannot be sent for 120msec



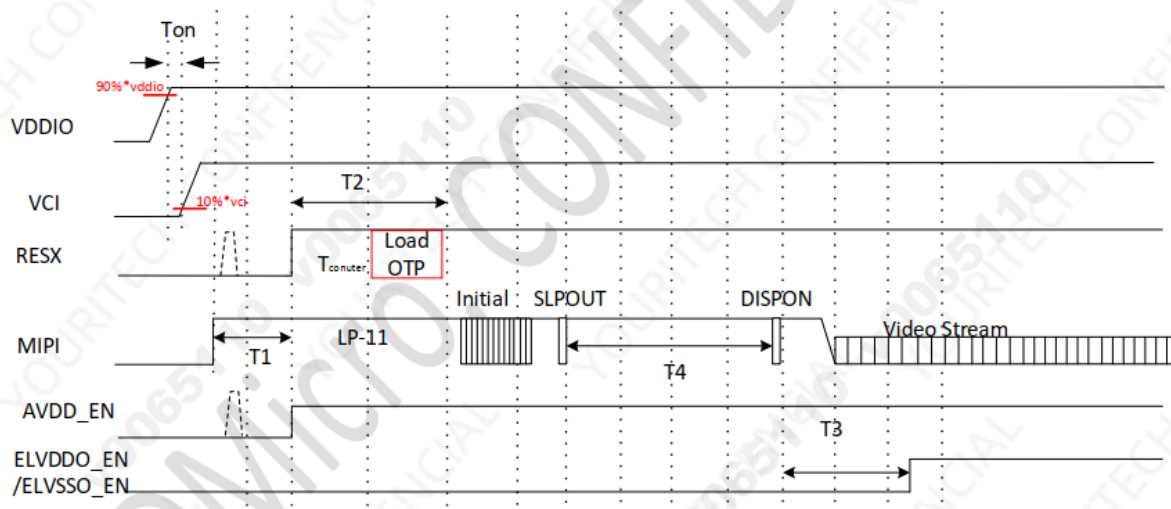
6 Recommended Operating Sequence

6.1 Display Power on / off Sequence

Timing Specification of Power On/Off Sequence

Sybol	Min	Typ	Max	Unit
Ton	0	-	-	ms
T1	1			ms
T2	12			ms
T3		3 frames		ms
T4	50			ms
T5	2 frames			ms
T6	50			ms
T7	1			ms

6.1.1 Power On Sequence



Note: 1.Ton: The time between the VDDIO and the VCI power on, $T_{on} \geq 0$ ms

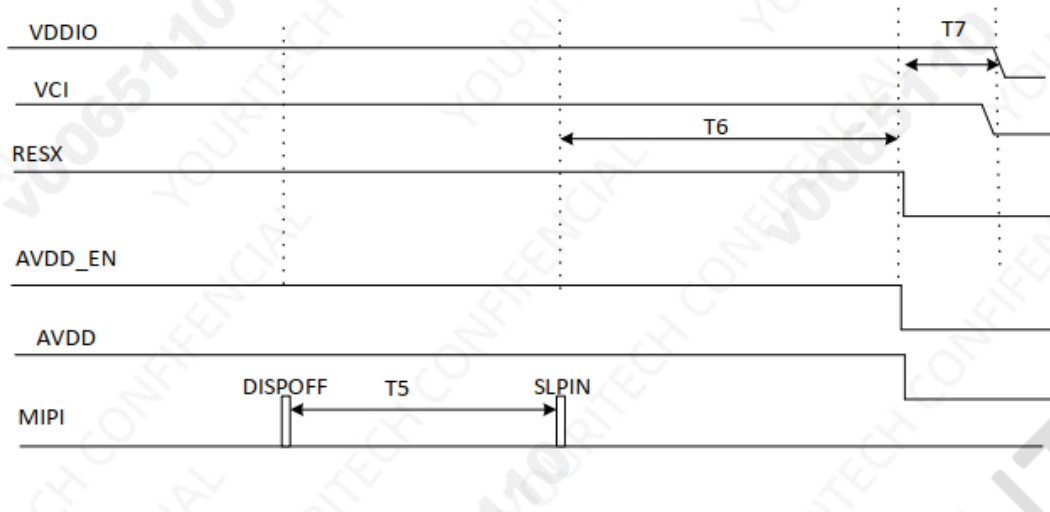
2.Dotted line is optional.

3. All the power supplies should be stable during display on status.

4. Current of VDDIO, VCI, AVDD should be less than 150mA respectively.

6.1.2 Power Off Sequence





7 Touch Specification

7.1 General Specifications

NO	ITEM	SPEC	REMARK
1	Accuracy @D7mm Finger(mm)	Center $\leq$ 1.0mm, Edge $\leq$ 1.5mm;	
2	Linearity @ D7mm Finger(mm)	Center $\leq$ 1.0mm, Edge $\leq$ 1.5mm;	
3	Jitter @D7mm Finger(mm)	ALL $\leq$ 1.0mm	
4	灵敏度@D7mm Finger(mm)	w/o line broken	
5	Report Rate	Typ. 120Hz, Max 240Hz	
6	Touch Point	Max 10 Fingers	

7.2 Electrical Characteristics

7.2.1 Maximum Ratings

Item	Symbol	MIN	MAX	Unit
TSP power supply Input	TSP_AVDD	2.7	3.6	V
TSP power supply for logic circuits	TSP_VDDIO	1.7	3.6	V

7.2.2 Power supply DC characteristics

Item	Symbol	MIN	TYP	MAX	Unit
TSP power supply Input	TSP_AVDD	2.8	2.8/3.0/3.3	3.6	V
TSP power supply for logic circuits	TSP_VDDIO	1.7	1.8/TSP_AVDD	3.6	V

7.3 TP FPC Pin Assignment

No	Symbol	I/O	Description
1	GND	Power	Ground
2	TSP_AVDD	Power	Analog Power for Touch Panel
3	TSP_VDDIO	Power	Digital Power for Touch Panel
4	TSP_INT	I/O	Interrupt Signal for Touch Panel
5	TSP_SDA	I/O	Serial Data Signal for Touch Panel I2C I/F
6	TSP_SCL	I/O	Serial Clock Signal for Touch Panel I2C I/F
7	TSP_RESET	I/O	Reset Pin for Touch Panel
8	GND	Power	Ground



7.4 Touch Design

Item		Description	Notes
Touch Design	Sensor structure	Oncell	
	Sensor pitch	Tx:4.549mm , Rx:4.473mm	
	Sensor pattern	Diamond	
	CH Number	15(Tx) / 33(Rx)	
	Trace mode	2T1R	

7.5 TSP FPC Electronic Part List

Item	Reference	Specification
1	C1 C2 C3 C4	1uF/6.3V/0402
2	C5	1uF/16V/0402
3	C6	1uF/10V/0402
4	D1	Bi-directional /5V/0402
5	D2	Bi-directional /3.3V/0402
6	R1 R2	4.7KΩ/0402
7	U1	Touch IC ,FT3519



8 Optical Characteristics Optical Specification

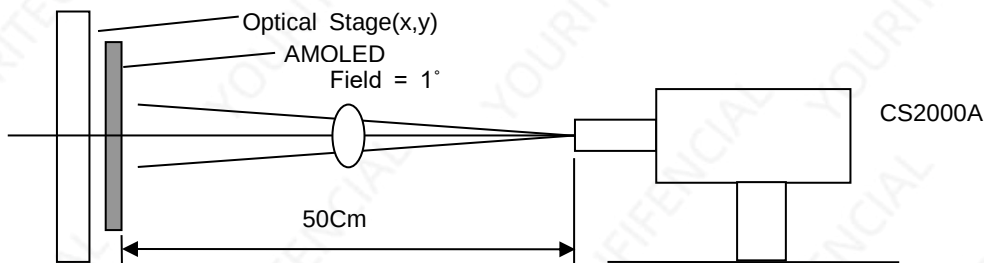
Item	Symbol	Condition	Min	Typ	Max	Unit	Remark
Luminance	L		450	500	550	Cd/m ²	
Chromaticity	white	x		(0.300)			
		y		(0.315)			
	Red	x	(0.652)	(0.682)	(0.712)		
		y	(0.285)	(0.315)	(0.345)		
	Green	x	(0.200)	(0.240)	(0.280)		
		y	(0.676)	(0.716)	(0.756)		
	Blue	x	(0.108)	(0.138)	(0.168)		
		y	(0.018)	(0.048)	(0.078)		

Test Conditions:

1. The ambient temperature is 25℃.
2. The test systems refer to Note1 and Note2.

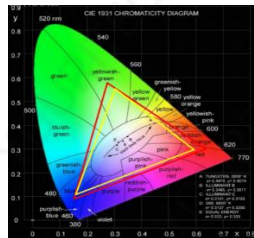
Note 1: Definition of optical measurement system.

The optical characteristics should be measured in dark room. The optical properties are measured at the center point of the AMOLED screen. All input terminals AMOLED panel must be ground when measuring the center area of the panel.



Note 2: Definition of color chromaticity (CIE1931)

Color coordinates measured at center point of AMOLED.



9 Environmental / Reliability Test

No	Test Item	Condition	Remark
1	High Temperature Operation	+70℃, 120hrs	IEC60068-2-2,GB2423.2
2	Low Temperature Operation	-20℃, 120hrs	IEC60068-2-1 GB2423.1
3	High Temperature Storage	+80℃, 120hrs	IEC60068-2-2 GB2423.2
4	Low Temperature Storage	-40℃, 120hrs	IEC60068-2-1 GB2423.1
5	High Temperature & High Humidity Operation	60℃, 90% RH,120hrs	IEC60068-2-78 GB/T2423.3
6	Thermal Shock (Non-operation)	-40(℃)/30(min) ~+80 (℃)/30(min), Change time:10min, 30Cycles	Start with cold temperature, End with high temperature, IEC60068-2-14,GB2423.22

Note: Product reliability items in the form of GK are used as reference items. The test results shall refer to the results of the reliability test of YOURITECH standards.



10 Quality Level

10.1 AMOLED Module of Characteristic Inspection

The environmental condition and visual inspection shall be conducted as below:

10.1.1 Test conditions: OLED is not light, cold white fluorescent lamp, illumination 1000 ± 200 lux; OLED lighting source shall not be higher than 200lux, with black background around.

10.1.2 Inspection distance: the standard observation distance of all surfaces of the tested object is $30\text{cm} \pm 5\text{cm}$.

10.1.3 Inspection angle: the angle between the product and the horizontal plane is 45° , and the eyes are perpendicular to the inspection plane. During inspection, the product needs to rotate 45° up, down, left and right. The observation line of sight needs to be within the half section of the cone. The observation angle is 45° with the vertical axis of the product apex. The central axis of the cone must be standard and perpendicular to the product surface and pass through the fluorescent lamp; For non-conventional display defects (including but not limited to local bright lines or local floodlights), the observation angle is 75 degrees from the normal of the product surface; Full visual angle of appearance.

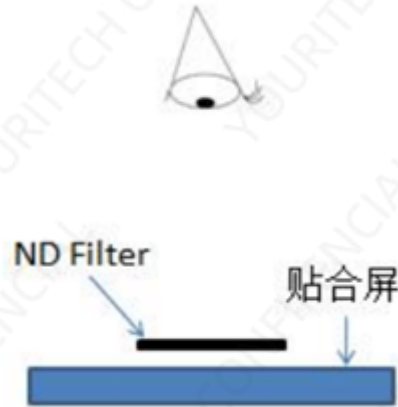
10.1.4 Inspection time: the inspection time without lighting is at least 10-12 seconds; The time of OLED lighting inspection for each picture is 1~3 seconds. If the defect is still not visible within the specified time, the inspection piece is deemed to be qualified.

10.1.5 Test temperature: room temperature $15-35^\circ\text{C}$, ambient humidity: 20-75% RH.

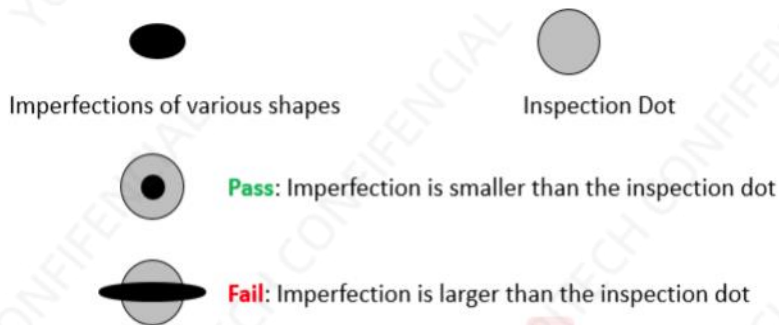
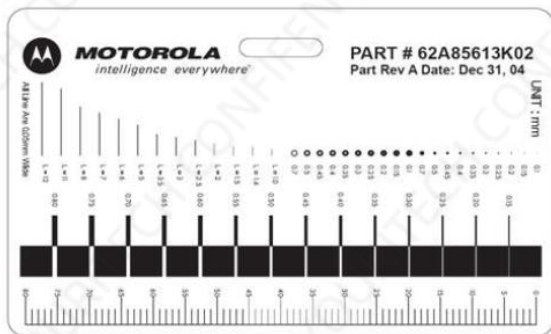
10.1.6 Inspection tools:

10.1.6.1 ND Filter: The ND Filter is placed at a distance of 2-3 cm above the defect for 2-3s to judge whether the defect is visible. As Figure below: (ND Filter is used to test mura isochromatic and light unevenness)





10.1.6.2 Point gauge (point gauge in the figure below is recommended), determination method: as shown in the figure, the point gauge film can cover is pass, and the point gauge film can not cover is Fail. For example, a maximum of 0.2mm same-color spot defect is allowed on the Class A surface, and the pass that can be covered by 0.2mm on the film, The one that can be covered is Fail.



10.1.6.3 Microscopic examination: use 20-50 times adjustable microscope and 10-30 times test eyepiece.

10.1.6.4 Digital caliper: resolution 0.01mm.

10.1.6.5 Projector: anime microscope, 3D projector.

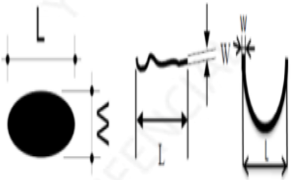
10.1.6.6 Judgment description



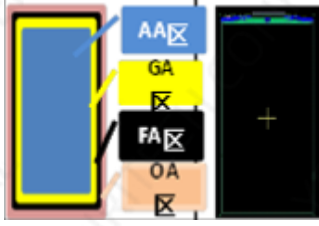
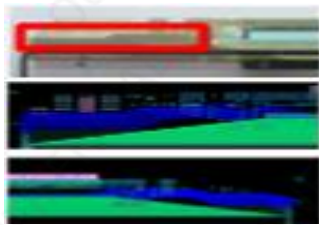
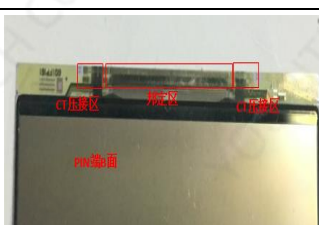
10.1.6.6.1 The measurement accuracy shall refer to the specification definition. When the measurement equipment accuracy is higher than the specification definition, the measured value needs to be rounded to the precision defined by the specification. For example, the size of edge collapse is 0.20mm, and the thousandth is the reference position, which is rounded to 0.200mm~0.204mm is OK, $\geq 0.205\text{mm}$, it is judged as NG.

10.1.6.6.2 In addition to the tools used above, if additional inspection tools are needed to assist the judgment, they can only be carried out after the coordination of both parties.

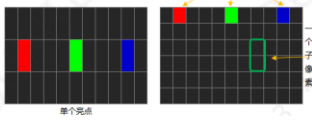
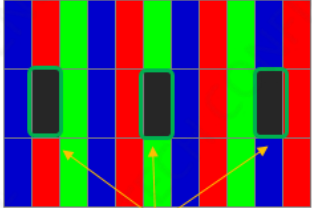
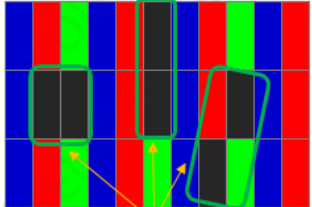
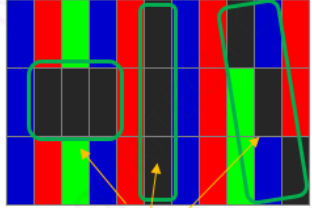
10.1.6.6.3 Bad code and definition

Code and name		legend	explain
N	Number	-	Visually calculate the number; The statistics of the total number of defects does not include the completely "omitted" part. For the column defined as "omitted" and "omitted", it is not counted as the number of defects if it meets the requirements, otherwise it is calculated as an independent defect.
L	Length (mm)		Dot line distinguishing rule: L is the long side, W is the short side A. When $L > 3W$, handle as per line, otherwise
W	Width (mm)		handle as per point; B. When it is judged as line defect, S-shaped or C-shaped line appears, and the enclosed amount is less than 3/4 circle, it shall be treated as line defect; otherwise, it shall be treated as point defect, and the inner tangent circle shall simulate the size of point.
S	Area (mm^2)	-	Surface gauge
D	Diameter (mm) $D=(L+W)/2$	-	Point diameter calculation: calculated by half of the sum of the long side and the short side, that is,

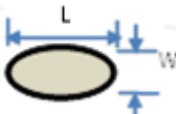
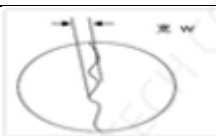
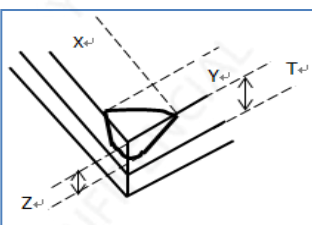


			$D=(L+W)/2$, where D represents the diameter of the point, L is the long side, and W is the short side;
H	Depth (mm)	-	Digital micrometer
DS	Distance (mm)		Distance between two points or between two lines
Schematic diagram of screen area			AA area: display area; GA area: GIP circuit area; FA area: Frit area; OA area: outside FA area
Leader area			Screen GIP circuit area, screen data circuit area
PAD Bangding District			COG/FOG Bonding alignment mark and Bonding Pad on LTPS substrate
PAD Non-state area			Screen test pad, cutting area and lead-free area on LTPS substrate
CT crimping area			Pin end screen test pad



Highlights		A single sub-pixel (or red, or green, or blue) of one pixel is called a point; The definition of bright spot is that in the environment of 200 ± 50 Lux, the pixels or dots seen by employees with naked eyes are always bright, and the bright spot is checked under the black screen
Scotoma		A single sub-pixel (or red, or green, or blue) of one pixel is called a point; A dark point is defined as a point that is not bright in a single sub-pixel seen with naked eyes in a 100% white picture under the environment of 200 ± 50 Lux.
Dark spot - two connection		Two adjacent sub-pixels under the magnifying glass are not bright at the same time (horizontal, vertical and oblique)
Dark Spot - Three Links		The adjacent R, G and B sub-pixels under the magnifying glass are not bright at the same time (horizontal, vertical and oblique)
CG monomer area division		AA: Front visible area, black ink internal area; A: Black ink area; B: Cover plate edge; The front defect that runs through the AA area and the A area shall be judged according to the specification of the strictest area, and the back defect shall be judged according to whether the AA area is visible.
Foreign matter highlights	-	Due to the foreign matter in the polarizer, the phenomenon that appears as a bright spot is called a foreign matter bright spot



point defect		There are bright spots and black spots in local positions, including but not limited to the internal dirt of the screen itself, pinholes, serrations, concave-convex spots, color spots, tiny bubbles, white spots, stains on the fitting of the polarizer, poor polarizer itself and other spot-like defects. Point defects are judged by diameter.
Linear defect		Linear impurities in the screen, including filaments, fibers, polarizer fitting impurities in the screen, and scratches on the surface of polarizer, etc. Linear defects are judged by length and width. Sensible scratch: also known as hard scratch, is a deep scratch on the surface, which is felt by hand. Senseless scratch: also known as fine scratch, no deep scratch on the surface, no feeling when touching.
Serrated defect		W: Distance from sawtooth crest to trough
Edge collapse/angle collapse		In the process of screen production, especially in the process of molding and cutting, the small glass missing at the glass edge is caused. X direction: parallel to FOG Pad or glass edge; Y direction: perpendicular to FOG Pad or glass edge; Z direction: screen thickness direction; T : The thickness of single-layer glass;
Pitting	-	In the unit area of 10mm * 10mm, the defect point with $D \leq 0.1\text{mm}$, $DS \geq 2\text{mm}$, and the number $N \geq 5$. If the customer has other requirements, follow the customer's requirements.



Dirty	-	Including handprints, oil stains, fingerprints, stains, white fog and other undesirable phenomena. It is divided into erasable dirt and non-erasable dirt. Use a dust-free cloth dipped in alcohol, which can not be erased as non-erasable dirt. Wipable dirt is determined as follows: A. Dry dust-free cloth can be directly erased; B. Wipe with clean cloth dipped with anhydrous alcohol Press the alcohol-stained dust-free cloth on the dry dust-free cloth twice to absorb excess alcohol; Wipe back and forth with a dust-free cloth twice, and the dirt can be removed.
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10.2 Sampling Procedures for Each Item Acceptance Table

Critical Defect (CR): any defect that directly or indirectly affects human health and safety, or the function of the product is lost.

Major Defect (MA): directly or indirectly affect the product function, or make part of the product function lost, and other customers do not acceptable defects.

Minor Defect (MI): appearance defect that does not affect product function and can be accepted by customers.

Defect Type	Sampling Procedures	AQL
Critical Defect (CR)	Take the normal inspection solution of the sampling plan of GB/T2828.1-2012 Inspection level II	0.065
Major Defect (MA)	Take the normal inspection solution of the sampling plan of GB/T2828.1-2012 Inspection level II	0.65
Minor Defect (MI)	Take the normal inspection solution of the sampling plan of GB/T2828.1-2012 Inspection level II	1.0

10.3 Telecommunications Inspection Item

category	NO.	Inspection items	Inspection specification	test mode	defect type
	1	Display exception	not allow	visual	CR



Poor function	2	No display	not allow	visual	CR
	3	The picture flickers	not allow	visual	MA
TP function	4	TP test NG	not allow	visual	MA
Dot	5	Bright dot	not allow	visual	MI
	6	Partial Bright dot	ND6% or reference limit sample	visual	MI
	7	Dark dot	1.D≤0.15mm, ignored; 2.0.15mm < D≤ 0.2mm, DS ≥ 10mm, N ≤ 10; 3.D > 0.2mm, not allowed;	Visual inspection, Flinka	MI
Line	8	Bright line	not allow	visual	MA
	9	Dark line	not allow	visual	MA
	10	Slightly bright line	not allow	visual	MA
Mura	11	horizontal mura	No control under W64/127 screen; The 4%ND Filter on the 255 screen determines that the invisible is OK and the visible is NG.	Visual ND Filter/limit sample	MI
	12	vertical mura	No control under W64/127 screen; The 4% ND Filter on the 255 screen determines that the invisible is OK and the visible is NG.	Visual ND Filter/limit sample	MI
	13	White spot	No control under W64/127 screen; The 4% ND Filter on the 255 screen determines that the invisible is OK and the visible is NG.	Visual ND Filter/limit sample	MI
	14	Black spot	No control under W64/127 screen; The 4% ND Filter on the 255 screen determines that the invisible is OK and the visible is NG.	Visual ND Filter/limit sample	MI
	15	Color mura	4% ND Filter in W64/255 screen determines that the invisible is OK and the visible is NG	Visual ND Filter/limit sample	MI

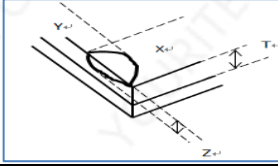


	16	snowflake	No control under W64/127 screen; The 4% ND Filter on the 255 screen determines that the invisible is OK and the visible is NG.	Visual ND Filter/limit sample	MI
	17	Twill mura	No control under W64/127 screen; The 4% ND Filter on the 255 screen determines that the invisible is OK and the visible is NG.	Visual ND Filter/limit sample	MI
	18	Newtonian ring	No control under W64/127 screen; The 4% ND Filter on the 255 screen determines that the invisible is OK and the visible is NG.	Visual ND Filter/limit sample	MI
	19	Uneven transition	Reference homogeneity standard to assist in judgment; The 4% ND Filter in the W64/255 screen determines that the invisible product is OK and the visible product is NG.	Visual ND Filter/limit sample	MI
	1、 Mura all specify the screen judgment. For example, if the ELA mura judgment standard is 255, the ELA mura will only be judged on the W255 screen. 2、 Other types of mura have a low adverse effect rate and low incidence. According to the 4% ND Filter in the W64/255 screen, the invisible products are OK and the visible ones are NG.				
Dot/line of foreign material	20	Dot/line defects (foreign material, black white dot, scratch, bubble, etc.)	Same point/line specifications	Visual inspection/Flinka	MI

10.4 Appearance Inspection Item

NO.	Inspection items	Surface Area	Inspection specification	test mode	defect type
1	Broken glass	AA/OA	not allow	visual	MA
2	crack	AA/OA	not allow	visual	MA
3	Edge collapse/corner	AA/OA	1. $Y \leq 0.15\text{mm}$, X and N are ignored; 2. $0.15 < Y \leq 0.4\text{mm}$, $X \leq 2\text{mm}$, N is ignored; 3. $Y > 0.4\text{mm}$, not allowed; 4. $Z \leq t$, without damage to Frit body;	Visual inspection, Flinka	MI



					
4	flange	AA/OA	1. $Y \leq 0.2\text{mm}$, X is uncontrolled; 2. $Y > 0.2\text{mm}$, not allowed; 	Visual inspection, Flinka	MI
5	Glass warp	Whole area	 The product is placed horizontally on the front and back, and the lifting height at one end (plug gauge) $\leq 0.6\text{mm}$	Visual inspection, Flinka	MI
6	Pin dirty	Bongding area	No control	visual	MI
7	Pin scratch	Bongding area	Scratches and whitening are found by visual inspection, and need to be rechecked with a microscope. The broken lead is not allowed, and the overlap is not allowed Note: CT pad area and pin non-bonding area are not controlled	visual	MI
8	PF film bump	LTPS	Touch is not allowed	visual	MI
9	PF film pinholes/pits	LTPS	No control	visual	MI
10	PF film scratch	LTPS	1. No scratch, no control; Scrape through, $L < 10\text{mm}$; 2. The film shall be scraped through the exposed glass surface, referring to the lack of glue of PF film;	Visual inspection, Flinka	MI
11	PF film lacks glue	LTPS	$50 > 5\text{mm}$, $W > 5\text{mm}$ not allowed	Visual inspection, Flinka	MI
12	PF membrane is dirty	LTPS	Wipable dirt needs to be wiped, and non-wipe dirt refers to the color difference of PF film;	visual	MI
13	PF film overflow	LTPS	1. Edge overflow $W < 0.2\text{mm}$, acceptable; 2. $W > 0.2\text{mm}$, not allowed;	Visual inspection, Flinka	MI



14	Color difference/stain (no convex touch)	LTPS	No control				visual	MI
15	PF film gluing offset	LTPS	1. Step area is not allowed; 2. Except for the step area, the rest shall be controlled by $0.5 \pm 0.2\text{mm}$;				Visual inspection, Flinka	MI
16	Screen body is dirty	LTPS	1. The front can be wiped and the dirt can be wiped, and the polarizer of the dirt cover cannot be wiped; 2. The back is not controlled;				visual	MI
17	point defect	AA	D (mm)	DS (mm)	Acceptable number		Visual inspection, Flinka	MI
			$D \leq 0.15\text{mm}$	/	Ignore			
			$0.15\text{mm} < D \leq 0.2\text{mm}$	$DS \geq 10$	$N \leq 10$			
18	Linear defect/foreign matter linear/non-inductive scratch	AA	W (mm)	L (mm)	DS (mm)	Acceptable number	Visual inspection, Flinka	MI
			$W \leq 0.03$	$L \leq 5$	≥ 10	ignore		
			$0.03 < W \leq 0.05$	$L \leq 2$	≥ 10	ignore		
			$0.03 < W \leq 0.05$	$2 < L \leq 5$	≥ 10	$N \leq 4$		
			$W > 0.05$	-	/	Not allowed		
			-	$L > 5$	/	Not allowed		
19	Point/Line defects	Camera hole area/Blind hole area	D(mm)		Acceptable number		Visual inspection, Flinka	MI
			$D \leq 0.15$		ignore			
			$0.15 < D \leq 0.2$		ignore			
			$D > 0.2$					
20	Newton rings (Blind hole area)	Camera hole area/Blind hole area	Not control				Visual inspection	MI
21	offset	Camera hole	The metal ring extends inward 0.1mm ,ignore				Visual inspection	MI



		area/Blind hole area			
22	Blind hole color bias(same color)	Camera hole area/Blind hole area	Functional requirements such as transmittance and PV value are met, not control appearance	Visual inspection	MI
23	Protective film scratch	Whole area	No control under no hurt boby	Visual inspection	MI
24	Protective film starved/overflow glue/burr	Whole area	No control under no hurt boby	Visual inspection	MI
25	Dirt inside the protective film	Whole area	Not allowed	Visual inspection	MI
26	Easy to tear	Cover front	Function is invalid, damaged, leaked not allowed Wrinkles, bumps, dirt, punching bad, burr, overflow glue is not controlled	Visual inspection	MI
27	Polarizer edge overflow	AA	$W \leq 0.35\text{mm}$, Not control; $W > 0.35\text{mm}$, Not allowed.	Visual inspection, Flinka	MI
28	Polarizer concave convex point	AA	convex point: $D \leq 0.2\text{mm}$ or refer to limit sample concave point: $D \leq 3\text{mm}$, $DS \geq 10\text{mm}$, $N \leq 3$ or refer to limit sample	Visual inspection, Flinka	MI
29	Polarizer fold / indentation	AA	Does not affect the display as OK or refer to limit sample;	Visual inspection	MI
30	Polarizer chromatism	AA	No control	Visual inspection	MI
31	IC chip	IC	Not allowed	Visual inspection	MI
32	FPC body defect	FPC	1. The parts on the FPC must be consistent with the product BOM table, and there are incorrect, multiple, or missing parts, which are not allowed; Polarities such as capacitors and inductors should not be soldered backwards or crooked; 2. FPC scratches/scratches are based on the absence of exposed copper; 3. Creases/Indentations: Indentations in the circuit area should not cause the back of the	Visual inspection	MI



			covering film to turn white; Non line area indentation should not cause FPC damage 4. Except for the golden finger. FPC foreign object: a. Spot shape: $D \leq 0.5\text{mm}$, $N \leq 3$; b. Linear: length and width $\leq 0.3 * 5\text{mm}$;		
33	FPC gold finger defect	Golden Finger Region	1. Golden finger cracking: The length and width of the crack/damage at the top of the golden finger $\leq$ the line width; 2. Gold finger copper leakage: $W \leq 1/3$ line width, $L \leq$ line width, unlimited quantity 3. Gold finger gap $W1 \leq 1/3$ line width W , length $L1 \leq 1/2$ line width W , unlimited quantity, all of the above conditions are met and allowed; 4. Gold finger pressure/scratch should not expose copper, there should be no unevenness, and there should be no depth visible to the naked eye, which does not affect assembly and is acceptable; 5. Gold fingers should not have sharp creases or dead folds; 6. FPC gold fingers should not have oxidation, blackening, burns, or browning;	Visual inspection	MI
34	connector	connector	There should be no tin or residual solder beads on the connector, and there should be no tin connection on the connector pins; PIN deformation shall be controlled within 0.05mm; Does not affect the lighting function; Visual inspection of pin breakage, pin detachment, and deformation of the outer frame is not allowed;	Visual inspection	MI
35	Insulating tape	Bonding area	There must be no obvious wrinkles or bubbles	Visual inspection	MI
		Component area	1. Scratches and glue splashes are uncontrollable; 2. Do not wipe dirt or dirt; 3. The offset of the insulation tape should not exceed the edge of the product, and other requirements should be determined based on the drawing; 4. Burr edges, no control over glue overflow;		



			5. Damaged, incomplete, or missing labels are not allowed;		
36	Composite tape	All	1. It is not allowed for the composite tape to leak out of the edge of the screen body; 2. Folding of composite tape, light leakage during assembly, or affecting assembly and thickness are not allowed; 3. Damaged composite tape is not allowed; 4. The size of the composite tape cutting defect does not meet the requirements of the drawing and cannot be controlled; 5. Composite tape should not be wiped with dirt or foreign objects, and foreign objects should follow the dotted line standard; 6. The burrs of the composite tape should not exceed the edge of the screen body, regardless of control; 8. Composite adhesive tape with no control over glue splashes or overflow; 9. Composite tape bubbles: $D \leq 5\text{mm}$, N not included; 10. Composite tape bumps: acute angle bumps $D \leq 0.3\text{mm}$, $N \leq 3$; Smooth concave convex points $D \leq 0.8\text{mm}$, $N \leq 3$; 11. Composite tape foreign object (foreign object between copper foil and blue film): $D \leq 0.3\text{mm}$, $N \leq 3$; 12. Edge sawtooth of composite tape: 0.5 13. The color difference of the protective film in the composite tape is not controlled; 14. Copper foil indentation and dead bending in composite tape are not allowed, which does not affect assembly and thickness control; Or reference limit sample; 15. No control of foreign objects/dents in copper foil in composite tape;	Visual inspection	MI
37	OCA overflow	All	Not allowed within AA area; Externally visible: Control standard $\leq 0.15\text{mm}$	Visual inspection	MI

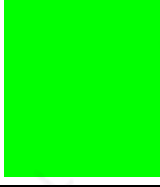


38	Sealing glue	Pin	1. Broken adhesive is not allowed, and the circuit cannot be exposed. 2. The thickness of the colloid shall not be higher than the POL surface. 3. Bubble diameter<1mm. 4. Other: According to the drawings and work instructions.	Visual inspection	MI
39	Conductive cloth	All	1. Conductive cloth dirt: $D \leq 5\text{mm}$, $N \leq 2$; 2. Conductive cloth bubbles: $D \leq 2\text{mm}$, $N \leq 2$; 3. Conductive cloth foreign object: $D \leq 1\text{mm}$, $N \leq 3$; 4. Folding of conductive fabric: $N \leq 2$;	Visual inspection	MI
40	Copper foil	All	Copper foil sticking is not allowed to leak out of the edge of the screen body; Abnormal color of copper foil refers to standard samples/sealed samples, and damage is not allowed. Soft scratches on the surface are not controlled.	Visual inspection	MI
41	QR code	QR code	It is not allowed to be unable to scan or difficult to scan (recognition can only be achieved after three consecutive scans), with a clear appearance, no blurring, missing printing, and other defects	Visual inspection	MI
42	Package	Other	Products should put into the anti-static trays, with non-overlapping, and the trays should be staggered placed. Different products cannot be mixed into the same inner package. The package should not have obvious deformation or breakage .The printing labels type and quantity are correct. The package should have QC signature. ROHS label is needed if the product is under ROHS control.	visual	-
43	Boundary dimension NG	Other	It is not allowed to exceed the dimensional tolerance required by the specifications and drawings	Calipers, measuring instruments	-

10.5 Inspection picture library

Serial number	picture	Picture name	Mainly judged as defective	remarks
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1		W_ GRAD(64) 64 gray scale	Point/line type, foreign matter point/line, mura type	/
2		W_ GRAD(128) 128 gray scale	Point/line type, foreign matter point/line, mura type	/
3		WHITE white	Point/line type, foreign matter point/line, mura type	/
4		Black black	Bright spot, bright line, dark mura	/
5		RED red	Point type, line type, foreign matter point/line	/
6		GREEN green	Point type, line type, foreign matter point/line	/
7		BLUE blue	Point type, line type, foreign matter point/line	/

Note: The actual sequence and lock seconds of the screen can be adjusted according to the customer's requirements and the needs of the factory.



[illegible]

12 Precautions for Use of AMOLED Modules

12.1 Handling Precautions:

- 12.1.1 The display panel is made of glass. Do not subject it to a mechanical shock by dropping it from height.
- 12.1.2 Do not press down the screen or the adjoining areas too hard because the color tone may be shifted.
- 12.1.3 The polarizer covering the display surface of the AMOLED module is soft and easily scratched. Handle this polarizer carefully.
- 12.1.4 If the display surface is contaminated, blow on the surface and gently wipe it with a soft dry cloth. If it is still not completely clear, moisten the cloth with ethyl alcohol.
- 12.1.5 Solvents may damage the polarizer. Do not use water, ketone or aromatic solvents except ethyl alcohol.
Do not attempt to disassemble the AMOLED Module.
- 12.1.6 If the logic circuit power is off, do not apply the input signals.
- 12.1.7 To prevent destruction from static electricity, be careful to maintain an optimum working environment.
- 12.1.8 Be sure to make yourself in contact with the ground when handling with the AMOLED Modules.
- 12.1.9 Tools required for assembly, such as soldering irons, must be properly ground.
- 12.1.10 To reduce the generation of static electricity, do not conduct assembly or other work under dry conditions.
- 12.1.11 To protect the display surface, the AMOLED Module is coated with a film. Be careful when peeling off this protective film, because static electricity may generate.

12.2 Storage Precautions:

- 12.2.1 When storing the AMOLED modules, be sure that they are not directly exposed to the sunlight or the light of fluorescent lamps.
- 12.2.2 The AMOLED modules should be stored under the storage temperature range. If the AMOLED modules will be stored for a long time, the recommended condition is:
Temperature: 0°C~40°C Relatively humidity: ≤80%
- 12.2.3 The AMOLED modules should be stored in the room without acid, alkali or harmful gas.

12.3 Transportation Precautions:

- 12.3.1 The AMOLED modules should not be suffered from falling and violent shocking during transportation. Besides, excessive press, water, damp and sunshine, should be avoided.

